RoHS

COMPLIANT HALOGEN

FREE



Vishay Semiconductors

Ultrafast Rectifier, 15 A FRED Pt®



LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS								
I _{F(AV)}	15 A							
V _R	600 V							
V _F at I _F	0.85 V							
t _{rr} (typ.)	60 ns							
T _J max.	175 °C							
Package	TO-220AC 2L							
Circuit configuration	Single							

FEATURES

- State of the art low forward voltage drop
- · Ultrafast soft recovery time
- 175 °C operating junction temperature
- Low leakage current
- True 2 pin package
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

DESCRIPTION

State of the art, ultralow V_F, soft-switching ultrafast rectifiers optimized for Discontinuous (Critical) Mode (DCM) Power Factor Correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimized the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

APPLICATIONS

AC/DC SMPS 70 W to 400 W

e.g. laptop and printer AC adaptors, desktop PC, TV and monitor, games units and DVD AC/DC power supplies.

MECHANICAL DATA

Case: TO-220AC 2L

Molding compound meets UL 94 V-0 flammability rating **Terminals:** matte tin plated leads, solderable per

J-STD-002

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	V_{RRM}		600	V
Average rectified forward current in DC	I _{F(AV)}	T _C = 157 °C	15	А
Non-repetitive peak surge current	I _{FSM}	T _J = 25 °C	200	
Operating junction and storage temperatures	T _J , T _{Stq}		-65 to +175	°C

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)										
PARAMETER	PARAMETER SYMBOL TEST CONDITIONS									
Breakdown voltage, blocking voltage	V _{BR} , V _R	Ι _R = 100 μΑ	600	-	-	.,				
Established	V _F	I _F = 15 A	=.	0.99	1.07	V				
Forward voltage		I _F = 15 A, T _J = 150 °C	=.	0.85	0.91					
Davis and Indiana assument	I _R	$V_R = V_R$ rated	-	0.01	15					
Reverse leakage current		= 150 °C, $V_R = V_R$ rated - 6 100		100	μΑ					
Junction capacitance	C _T	V _R = 600 V	-	12	-	pF				
Series inductance	L _S	Measured lead to lead 5 mm from package body	=	8	-	nH				



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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)										
PARAMETER	SYMBOL	TEST (CONDITIONS	MIN.	TYP.	MAX.	UNITS			
		$I_F = 1 A, dI_F/dt = 1$	00 A/μs, V _R = 30 V	-	60	110				
Reverse recovery time	t _{rr}	$I_F = 15 A$, $dI_F/dt =$	-	185	270					
heverse recovery time		T _J = 25 °C		-	210	-	ns			
		T _J = 125 °C		-	290	-				
Dook room ourrent	I _{RRM}	T _J = 25 °C	l _F = 15 A, dl _F /dt = 200 A/μs,	-	20	-	А			
Peak recovery current		T _J = 125 °C	$V_{\rm R} = 390 \text{ V}$	-	26	-				
Reverse recovery charge	Q _{rr}	T _J = 25 °C] ''	-	2.2	-	μC			
		T _J = 125 °C		-	4.0	-				

THERMAL - MECHANICAL SPECIFICATIONS										
PARAMETER	PARAMETER SYMBOL TEST CONDITIONS									
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C				
Thermal resistance, junction-to-case	R _{thJC}		-	1.2	1.4					
Thermal resistance, junction-to-ambient	R _{thJA}	Typical socket mount	-	-	70	°C/W				
Typical thermal resistance, case-to-heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-					
Weight			-	2	-	g				
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)				
Marking device		Case style TO-220AC 2L	ETL1506							



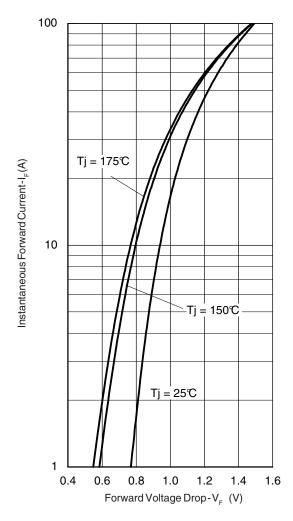


Fig. 1 - Typical Forward Voltage Drop Characteristics

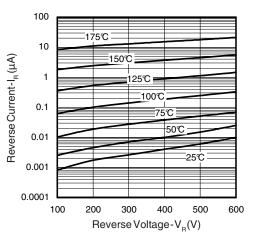


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

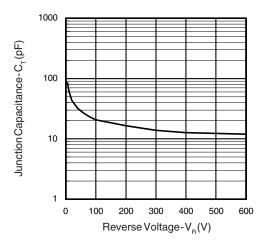


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

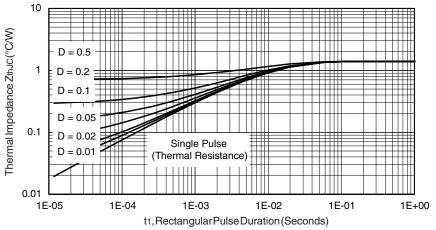


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics



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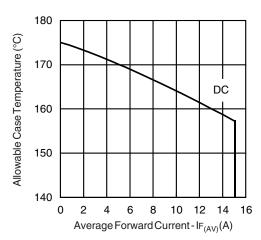


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

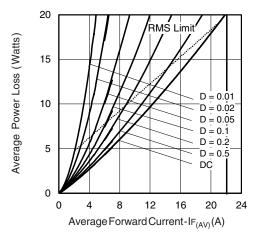


Fig. 6 - Forward Power Loss Characteristics

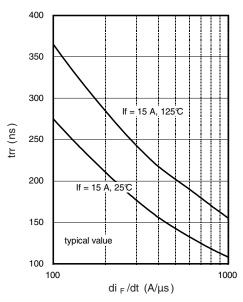


Fig. 7 - Typical Reverse Recovery vs. dI_F/dt

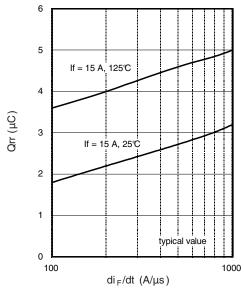
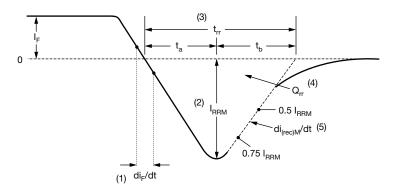


Fig. 8 - Typical Stored Charge vs. dl_F/dt



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- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_{F} to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) $\rm Q_{rr}$ area under curve defined by $\rm t_{rr}$ and $\rm I_{RRM}$

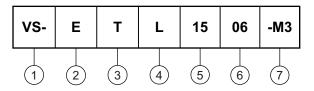
$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Circuit configuration:

E = single

3 - T = 2L TO-220AC

L = hyperfast recovery time

5 - Current code: 15 = 15 A

- Voltage code: 06 = 600 V

7 - Environmental digit:

-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)								
PREFERRED P/N	PACKAGING DESCRIPTION							
VS-ETL1506-M3	50	Antistatic plastic tubes						

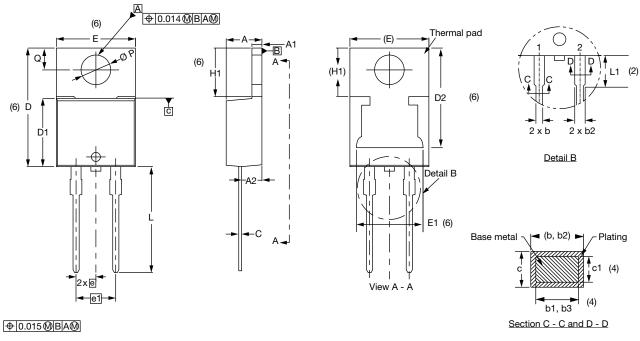
LINKS TO RELATED DOCUMENTS							
Dimensions <u>www.vishay.com/doc?96156</u>							
Part marking information	www.vishay.com/doc?95391						
SPICE model	www.vishay.com/doc?97052						



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TO-220AC 2L

DIMENSIONS in millimeters and inches



Lead tip

Conforms to JEDEC® outline TO-220AC

SYMBOL	MILLIN	MILLIMETERS INCHES		INCHES		NOTES		NOTES	SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES		STIVIBOL	MIN.	MAX.	MIN.	MAX.	NOTES		
Α	4.25	4.65	0.167	0.183			D2	11.68	13.30	0.460	0.524	6, 7		
A1	1.14	1.40	0.045	0.055			E	10.11	10.51	0.398	0.414	3, 6		
A2	2.50	2.92	0.098	0.115			E1	6.86	8.89	0.270	0.350	6		
b	0.69	1.01	0.027	0.040			е	2.41	2.67	0.095	0.105			
b1	0.38	0.97	0.015	0.038	4		e1	4.88	5.28	0.192	0.208			
b2	1.20	1.73	0.047	0.068			H1	6.09	6.48	0.240	0.255	6		
b3	1.14	1.73	0.045	0.068	4		L	13.52	14.02	0.532	0.552			
С	0.36	0.61	0.014	0.024			L1	3.32	3.82	0.131	0.150	2		
c1	0.36	0.56	0.014	0.022	4		ØΡ	3.54	3.91	0.139	0.154			
D	14.85	15.35	0.585	0.604	3		Q	2.60	3.00	0.102	0.118			
D1	8.38	9.02	0.330	0.355										

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3, and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2, and E1
- (7) Outline conforms to JEDEC® TO-220, except D2



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